

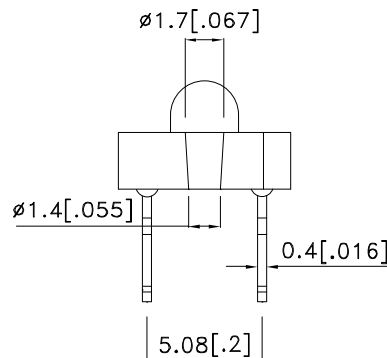
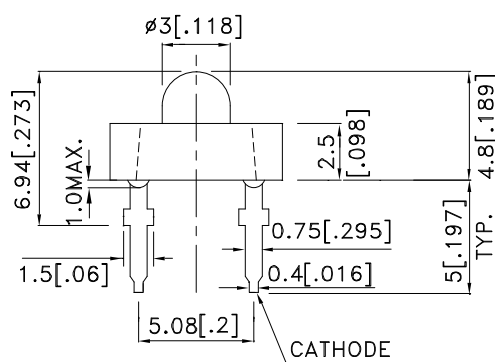
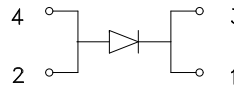
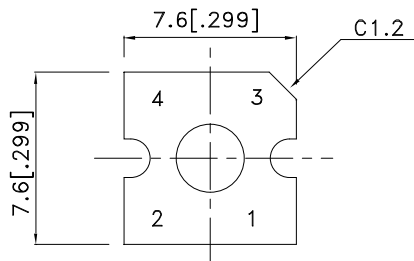
Features

- Super flux output.
- Design for high current operation.
- Outstanding material efficiency.
- Reliable and rugged.
- RoHS compliant.

Description

The Hyper Red source color devices are made with Al-GaN/P on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25 (0.01") unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2]* @ 20mA		Φv (mlm) [2] @ 20mA	Viewing Angle [1]
			Min.	Typ.	Typ.	2θ1/2
WP76761CSEC/E	Hyper Red (AlGaInP)	Water Clear	1900	3000	600	20°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%. *LEDs are binned according to their Luminous intensity.
3. Drive current between 10mA and 30mA are recommended for long term performance.
4. Operation at current below 10mA is not recommended.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	630		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red	621		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	20		nm	IF=20mA
C	Capacitance	Hyper Red	25		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red	2	2.5	V	IF=20mA
IR	Reverse Current	Hyper Red		10	uA	VR = 5V

Notes:

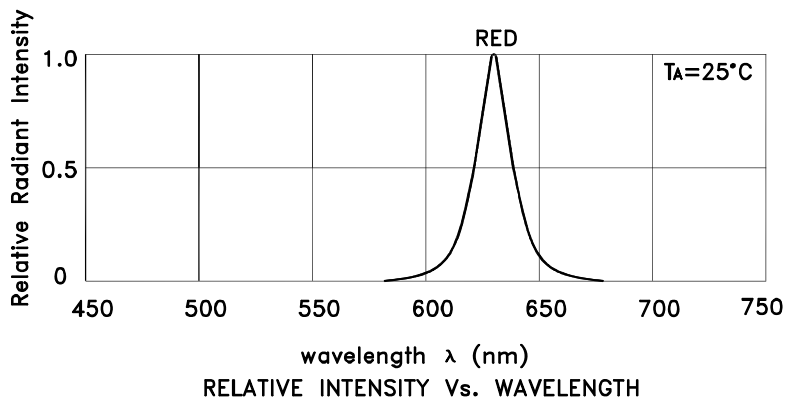
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	195	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	
Lead Solder Temperature [2]	260°C For 3 Seconds	
Lead Solder Temperature [3]	260°C For 5 Seconds	

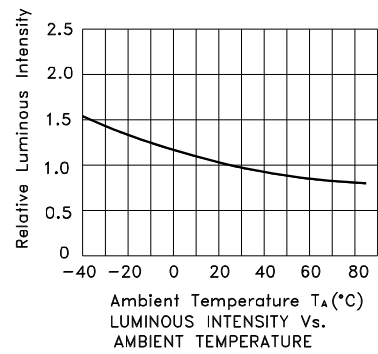
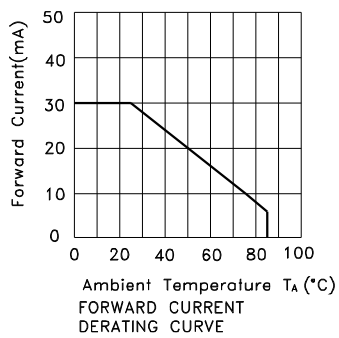
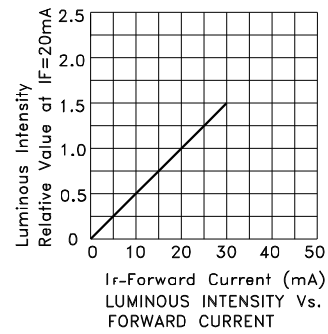
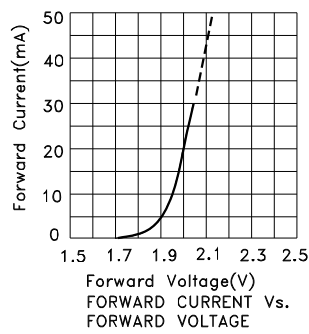
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.



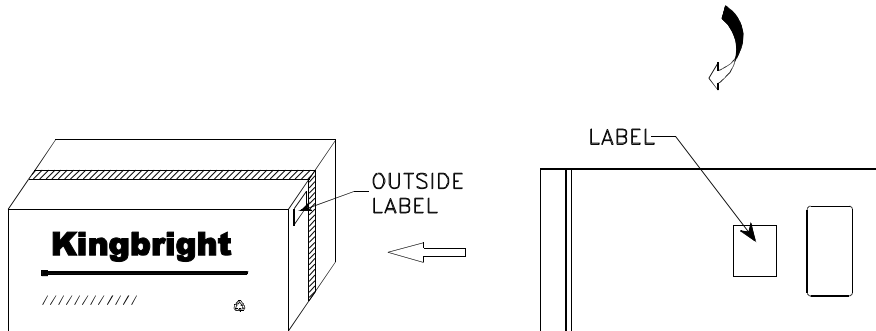
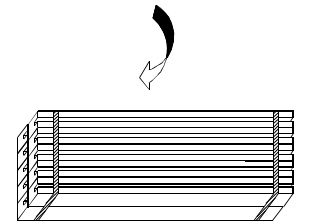
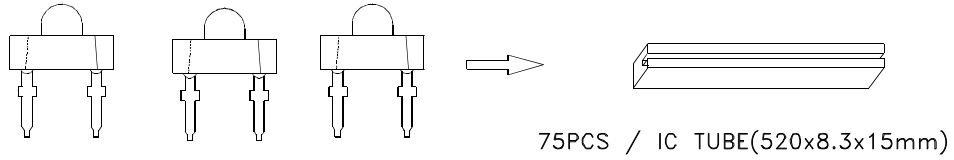
Hyper Red

WP76761CSEC/E




PACKING & LABEL SPECIFICATIONS

WP76761CSEC/E



7.5K / 6# BOX

10pcs IC TUBE / BAG

<h1>Kingbright</h1>	
P/NO: WP76761Cxxx	
QTY: 750 pcs	Q.C. Q C XX XX XXXX PASSED
S/N: XXXX	
CODE: XXX	
LOT NO:	
 XXXXXXXXXXXX	
RoHS Compliant	

PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



Fig.1

”○” Correct mounting method ”×” Incorrect mounting method

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)

3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



Fig. 2

Fig. 3

Fig. 4

4. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)

6. Do not bend the leads more than twice. (Fig. 8)



7. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



8. The tip of the soldering iron should never touch the lens epoxy.

9. Through-hole LEDs are incompatible with reflow soldering.

10. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.

11. Recommended Wave Soldering Profile for Kingbright Thru-Hole Products



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105°C.
5. No more than once.